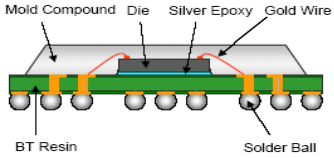


Material Declaration

Compliance Date: Jan./11/2023

RoHS Compliance: Yes

MSL: 3

Pin count /Package		48B BGA (6X8)								
Model (Part) Number		AS6C8016-55BIN								
Package Weight (mg)		130.050								
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part	
Chip	Wafer Circuit	13.56	10.43	104,268	Silicon (Si)	7440-21-3	13.560	10.427%	100.00%	
Bonding Wire	Conductivity	2.59	1.99	19,915	Gold (Au)	7440-57-5	2.590	1.992%	100.00%	
Die Attach	Die Attach	1.3	1.00	9,996	Acrylic resin (Die attach film)	(Trade secret)	0.436	0.335%	33.55%	
					Silica, amorphous (Die attach film)	7631-86-9	0.192	0.148%	14.77%	
					Phenol resin (Die attach film)	(Trade secret)	0.032	0.025%	2.46%	
					Polypropylene copolymer (Dicing Tape)	(Trade secret)	0.384	0.295%	29.53%	
					Acrylic resin (Dicing Tape)	(Trade secret)	0.192	0.148%	14.77%	
					Polyethylene copolymer (Dicing Tape)	(Trade secret)	0.064	0.049%	4.92%	
Substrate	Substrate	21.64	16.64	166,398	Copper (Cu)	7440-50-8	10.965	8.431%	50.67%	
					Nickel	7440-02-0	0.281	0.216%	1.30%	
					Gold (Au)	7440-57-5	0.065	0.050%	0.30%	
					Silicon oxide/BT Resin	65997-17-3	5.194	3.994%	24.00%	
					Bisphenol A Resin	80-05-7	0.050	0.038%	0.23%	
					Solder mask /Barium sulfate	7727-43-7	5.085	3.910%	23.50%	
Molding Compound	Chip Protection	83.26	64.02	640,215	Silica, vitreous (Alias : Silica(Fused))	60676-86-0 7631-86-9	74.518	57.299%	89.50%	
					Epoxy resin	(Trade secret)	4.163	3.201%	5.00%	
					Phenol resin	(Trade secret)	4.163	3.201%	5.00%	
					Carbon Black	1333-86-4	0.416	0.320%	0.50%	
Solder Ball	Solder	7.70	5.92	59,208	Tin (Sn)	7440-31-5	7.431	5.714%	96.50%	
					Silver (Ag)	7440-22-4	0.231	0.178%	3.00%	
					Copper (Cu)	7440-50-8	0.039	0.030%	0.50%	